

256K x 16 HIGH-SPEED CMOS STATIC RAM

MARCH 2008

FEATURES

HIGH SPEED: (IS61/64C25616AL)

- High-speed access time: 10ns, 12 ns
- Low Active Power: 150 mW (typical)
- Low Standby Power: 10 mW (typical) CMOS standby

LOW POWER: (IS61/64C25616AS)

- High-speed access time: 25 ns
- Low Active Power: 75 mW (typical)
- Low Standby Power: 1 mW (typical) CMOS standby
- TTL compatible interface levels
- Single 5V ± 10% power supply
- Fully static operation: no clock or refresh required
- Available in 44-pin SOJ package and 44-pin TSOP (Type II)
- Commercial, Industrial and Automotive temperature ranges available
- Lead-free available

DESCRIPTION

The *ISSI* IS61C25616AL/AS and IS64C25616AL/AS are high-speed, 4,194,304-bit static RAMs organized as 262,144 words by 16 bits. They are fabricated using *ISSI*'s high-performance CMOS technology. This highly reliable process coupled with innovative circuit design techniques, yields access times as fast as 12 ns with low power consumption.

When \overline{CE} is HIGH (deselected), the device assumes a standby mode at which the power dissipation can be reduced down with CMOS input levels.

Easy memory expansion is provided by using Chip Enable and Output Enable inputs, \overline{CE} and \overline{OE} . The active LOW Write Enable (\overline{WE}) controls both writing and reading of the memory. A data byte allows Upper Byte (\overline{UB}) and Lower Byte (\overline{LB}) access.

The IS61C25616AL/AS and IS64C25616AL/AS are packaged in the JEDEC standard 44-pin 400-mil SOJ and 44-pin TSOP (Type II).

FUNCTIONAL BLOCK DIAGRAM



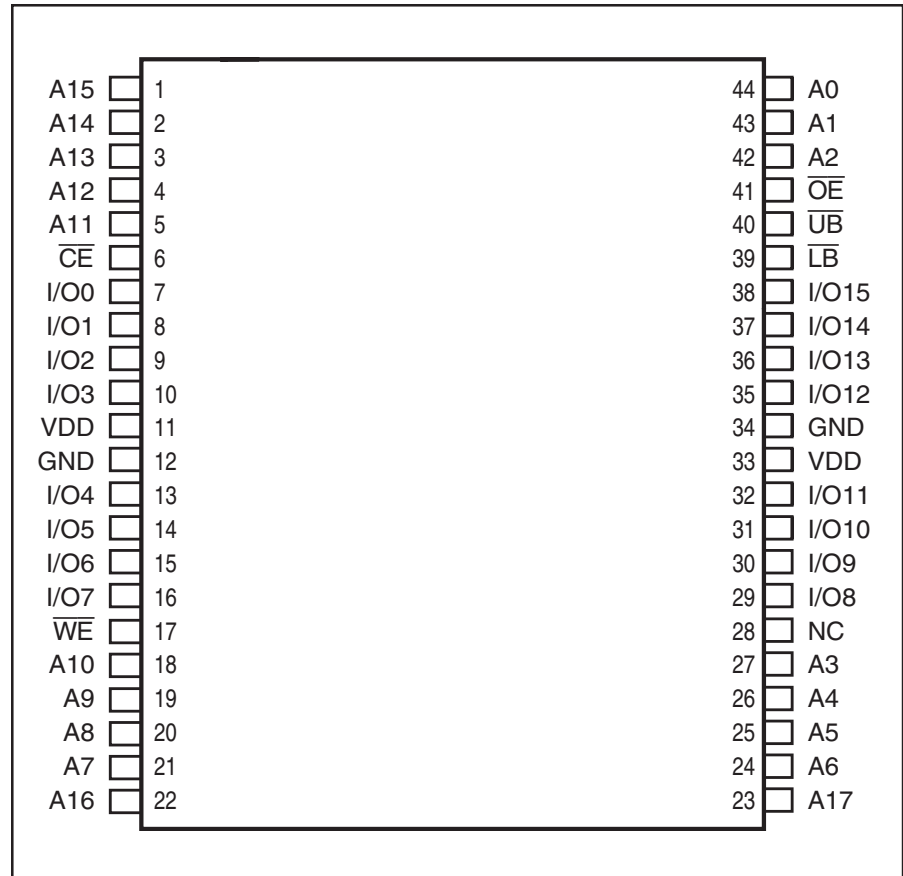
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PIN CONFIGURATIONS

44-Pin SOJ



44-Pin TSOP (Type II)



PIN DESCRIPTIONS

| | |
|-----------------|---------------------|
| A0-A17 | Address Inputs |
| I/O0-I/O15 | Data Inputs/Outputs |
| \overline{CE} | Chip Enable Input |
| \overline{OE} | Output Enable Input |
| \overline{WE} | Write Enable Input |

| | |
|-----------------|---------------------------------|
| \overline{LB} | Lower-byte Control (I/O0-I/O7) |
| \overline{UB} | Upper-byte Control (I/O8-I/O15) |
| NC | No Connection |
| VDD | Power |
| GND | Ground |

TRUTH TABLE

| Mode | \overline{WE} | \overline{OE} | \overline{OE} | \overline{LB} | \overline{UB} | I/O PIN | | V _{DD} Current |
|-----------------|-----------------|-----------------|-----------------|-----------------|-----------------|-----------|------------|-------------------------------------|
| | | | | | | I/O0-I/O7 | I/O8-I/O15 | |
| Not Selected | X | H | X | X | X | High-Z | High-Z | I _{SB1} , I _{SB2} |
| Output Disabled | H | L | H | X | X | High-Z | High-Z | I _{CC1} , I _{CC2} |
| | X | L | X | H | H | High-Z | High-Z | |
| Read | H | L | L | L | H | Dout | High-Z | I _{CC1} , I _{CC2} |
| | H | L | L | H | L | High-Z | Dout | |
| | H | L | L | L | L | Dout | Dout | |
| Write | L | L | X | L | H | Din | High-Z | I _{CC1} , I _{CC2} |
| | L | L | X | H | L | High-Z | Din | |
| | L | L | X | L | L | Din | Din | |

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

| Symbol | Parameter | Value | Unit |
|-------------------|--------------------------------------|--------------|------|
| V _{TERM} | Terminal Voltage with Respect to GND | -0.5 to +7.0 | V |
| T _{STG} | Storage Temperature | -65 to +150 | °C |
| P _T | Power Dissipation | 1.5 | W |
| I _{OUT} | DC Output Current (LOW) | 20 | mA |

Notes:

1. Stress greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

CAPACITANCE^(1,2)

| Symbol | Parameter | Conditions | Max. | Unit |
|------------------|--------------------|-----------------------|------|------|
| C _{IN} | Input Capacitance | V _{IN} = 0V | 5 | pF |
| C _{OUT} | Output Capacitance | V _{OUT} = 0V | 7 | pF |

Notes:

1. Tested initially and after any design or process changes that may affect these parameters.
2. Test conditions: T_A = 25°C, f = 1 MHz, V_{DD} = 5.0V.

DC ELECTRICAL CHARACTERISTICS (Over Operating Range)

| Symbol | Parameter | Test Conditions | Min. | Max. | Unit | |
|-----------------|----------------------------------|--|-------|-----------------------|------|----|
| V _{OH} | Output HIGH Voltage | V _{DD} = Min., I _{OH} = -4.0 mA | 2.4 | — | V | |
| V _{OL} | Output LOW Voltage | V _{DD} = Min., I _{OL} = 8.0 mA | — | 0.4 | V | |
| V _{IH} | Input HIGH Voltage | | 2.2 | V _{DD} + 0.5 | V | |
| V _{IL} | Input LOW Voltage ⁽¹⁾ | | -0.3 | 0.8 | V | |
| I _{LI} | Input Leakage | GND ≤ V _{IN} ≤ V _{DD} | Com. | -1 | 1 | μA |
| | | | Ind. | -2 | 2 | |
| | | | Auto. | -5 | 5 | |
| I _{LO} | Output Leakage | GND ≤ V _{OUT} ≤ V _{DD} Outputs Disabled | Com. | -1 | 1 | μA |
| | | | Ind. | -2 | 2 | |
| | | | Auto. | -5 | 5 | |

Note: 1. V_{IL} = -3.0V for pulse width less than 10 ns.

OPERATING RANGE: HIGH SPEED OPTION (IS61/64C25616AL)

| Range | Ambient Temperature | V _{DD} | Speed (ns) |
|------------|---------------------|-----------------|------------|
| Commercial | 0°C to +70°C | 5V ± 10% | 10 |
| Industrial | -40°C to +85°C | 5V ± 10% | 10 |
| Automotive | -40°C to +125°C | 5V ± 10% | 12 |

OPERATING RANGE: LOW POWER OPTION (IS61/64C25616AS)

| Range | Ambient Temperature | V _{DD} | Speed (ns) |
|------------|---------------------|-----------------|------------|
| Commercial | 0°C to +70°C | 5V ± 10% | 25 |
| Industrial | -40°C to +85°C | 5V ± 10% | 25 |
| Automotive | -40°C to +125°C | 5V ± 10% | 25 |

HIGH SPEED OPTION (IS61/64C25616AL)

POWER SUPPLY CHARACTERISTICS⁽¹⁾ (Over Operating Range)

| Symbol | Parameter | Test Conditions | | -10 ns | | -12 ns | | Unit |
|------------------|--|--|---------------------|--------|------|--------|------|------|
| | | | | Min. | Max. | Min. | Max. | |
| I _{CC1} | V _{DD} Operating Supply Current | V _{DD} = V _{DD MAX.} , $\overline{CE} = V_{IL}$ I _{OUT} = 0 mA, f = 0 | Com. | — | 45 | — | 45 | mA |
| | | | Ind. | — | 50 | — | 50 | |
| | | | Auto. | — | 55 | — | 55 | |
| I _{CC2} | V _{DD} Dynamic Operating Supply Current | V _{DD} = V _{DD MAX.} , $\overline{CE} = V_{IL}$ I _{OUT} = 0 mA, f = f _{MAX} | Com. | — | 50 | — | 45 | mA |
| | | | Ind. | — | 55 | — | 50 | |
| | | | Auto. | — | 70 | — | 60 | |
| | | | typ. ⁽²⁾ | 30 | 25 | | | |
| I _{SB1} | TTL Standby Current (TTL Inputs) | V _{DD} = V _{DD MAX.} , V _{IN} = V _{IH} or V _{IL} $\overline{CE} \geq V_{IH}$, f = 0 | Com. | — | 15 | — | 15 | mA |
| | | | Ind. | — | 20 | — | 20 | |
| | | | Auto. | — | 30 | — | 30 | |
| I _{SB2} | CMOS Standby Current (CMOS Inputs) | V _{DD} = V _{DD MAX.} , $\overline{CE} \leq V_{DD} - 0.2V$, V _{IN} $\geq V_{DD} - 0.2V$, or V _{IN} $\leq 0.2V$, f = 0 | Com. | — | 8 | — | 8 | mA |
| | | | Ind. | — | 12 | — | 12 | |
| | | | Auto. | — | 20 | — | 20 | |
| | | | typ. ⁽²⁾ | 2 | | | | |

Note:

- At f = f_{MAX}, address and data inputs are cycling at the maximum frequency, f = 0 means no input lines change.
- Typical values are measured at V_{DD} = 5V, T_A = 25°C and not 100% tested.

LOW POWER OPTION (IS61/64C25616AS)

POWER SUPPLY CHARACTERISTICS⁽¹⁾ (Over Operating Range)

| Symbol | Parameter | Test Conditions | | -25 ns | | Unit |
|------------------|--|--|---------------------|--------|------|------|
| | | | | Min. | Max. | |
| I _{CC} | Average operating Current | $\overline{CE} = V_{IL}$, V _{DD} = Max., I _{OUT} = 0 mA, f = 0 | Com. | — | 10 | mA |
| | | | Ind. | — | 15 | |
| | | | Auto. | — | 20 | |
| I _{CC1} | V _{DD} Dynamic Operating Supply Current | V _{DD} = Max., $\overline{CE} = V_{IL}$ I _{OUT} = 0 mA, f = f _{MAX} V _{IN} = V _{IH} or V _{IL} | Com. | — | 25 | mA |
| | | | Ind. | — | 30 | |
| | | | Auto. | — | 40 | |
| | | | typ. ⁽²⁾ | 15 | | |
| I _{SB1} | TTL Standby Current (TTL Inputs) | V _{DD} = Max., V _{IN} = V _{IH} or V _{IL} , $\overline{CE} \geq V_{IH}$, f = 0 | Com. | — | 1 | mA |
| | | | Ind. | — | 1.5 | |
| | | | Auto. | — | 2 | |
| I _{SB2} | CMOS Standby Current (CMOS Inputs) | V _{DD} = Max., $\overline{CE} \geq V_{DD} - 0.2V$, V _{IN} $\geq V_{DD} - 0.2V$, or V _{IN} $\leq V_{SS} + 0.2V$, f = 0 | Com. | — | 0.8 | mA |
| | | | Ind. | — | 0.9 | |
| | | | Auto. | — | 2 | |
| | | | typ. ⁽²⁾ | 0.2 | | |

Note:

- At f = f_{MAX}, address and data inputs are cycling at the maximum frequency, f = 0 means no input lines change.
- Typical values are measured at V_{DD} = 5V, T_A = 25°C and not 100% tested.

READ CYCLE SWITCHING CHARACTERISTICS⁽¹⁾ (Over Operating Range)

| Symbol | Parameter | -10 | | -12 | | -25 | | Unit |
|------------------|---|------|------|------|------|------|------|------|
| | | Min. | Max. | Min. | Max. | Min. | Max. | |
| t_{RC} | Read Cycle Time | 10 | — | 12 | — | 25 | — | ns |
| t_{AA} | Address Access Time | — | 10 | — | 12 | — | 25 | ns |
| t_{OHA} | Output Hold Time | 3 | — | 3 | — | 3 | — | ns |
| t_{ACE} | \overline{CE} Access Time | — | 10 | — | 12 | — | 25 | ns |
| t_{DOE} | \overline{OE} Access Time | — | 5 | — | 6 | — | 15 | ns |
| $t_{HZOE}^{(2)}$ | \overline{OE} to High-Z Output | 0 | 5 | 0 | 6 | 0 | 8 | ns |
| $t_{LZOE}^{(2)}$ | \overline{OE} to Low-Z Output | 0 | — | 0 | — | 2 | — | ns |
| $t_{HZCE}^{(2)}$ | \overline{CE} to High-Z Output | 0 | 5 | 0 | 6 | 0 | 8 | ns |
| $t_{LZCE}^{(2)}$ | \overline{CE} to Low-Z Output | 2 | — | 2 | — | 2 | — | ns |
| t_{BA} | $\overline{LB}, \overline{UB}$ Access Time | — | 5 | — | 6 | — | 25 | ns |
| t_{HZB} | $\overline{LB}, \overline{UB}$ to High-Z Output | 0 | 5 | 0 | 6 | 0 | 8 | ns |
| t_{LZB} | $\overline{LB}, \overline{UB}$ to Low-Z Output | 0 | — | 0 | — | 0 | — | ns |

Notes:

1. Test conditions assume signal transition times of 3 ns or less, timing reference levels of 1.5V, input pulse levels of 0 to 3.0V and output loading specified in Figure 1.
2. Tested with the load in Figure 2. Transition is measured ± 500 mV from steady-state voltage. Not 100% tested.
3. Not 100% tested.

AC TEST CONDITIONS

| Parameter | Unit |
|---|---------------------|
| Input Pulse Level | 0V to 3.0V |
| Input Rise and Fall Times | 3 ns |
| Input and Output Timing and Reference Level | 1.5V |
| Output Load | See Figures 1 and 2 |

AC TEST LOADS



Figure 1



Figure 2

AC WAVEFORMS

READ CYCLE NO. 1^(1,2) (Address Controlled) ($\overline{CE} = \overline{OE} = V_{IL}$, \overline{UB} or $\overline{LB} = V_{IL}$)



READ CYCLE NO. 2^(1,3)



Notes:

1. \overline{WE} is HIGH for a Read Cycle.
2. The device is continuously selected. \overline{OE} , \overline{CE} , \overline{UB} , or $\overline{LB} = V_{IL}$.
3. Address is valid prior to or coincident with \overline{CE} LOW transition.

WRITE CYCLE SWITCHING CHARACTERISTICS^(1,3) (Over Operating Range)

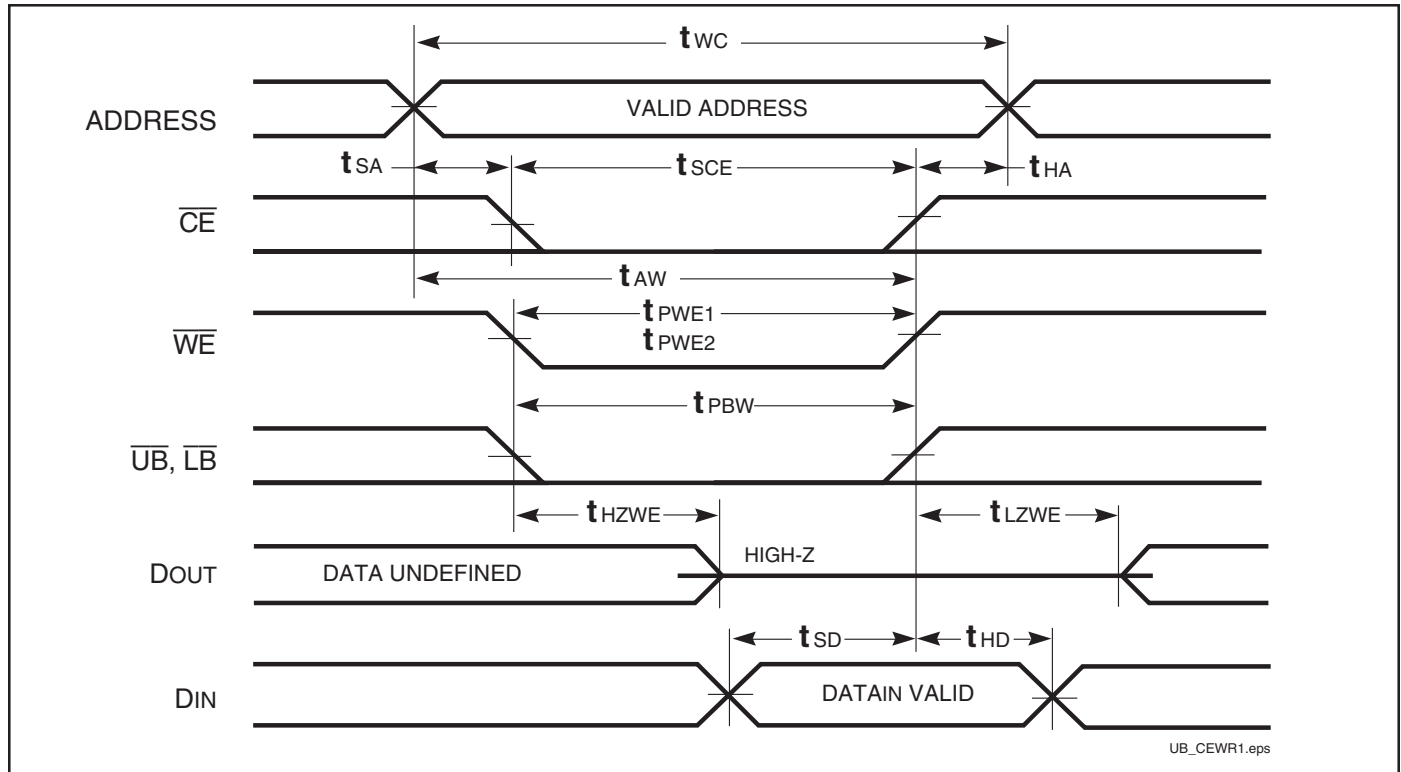
| Symbol | Parameter | -10 | | -12 | | -25 | | Unit |
|---------------------------------|---|------|------|------|------|------|------|------|
| | | Min. | Max. | Min. | Max. | Min. | Max. | |
| t _{WC} | Write Cycle Time | 10 | — | 12 | — | 25 | — | ns |
| t _{SCE} | \overline{CE} to Write End | 7 | — | 9 | — | 18 | — | ns |
| t _{AW} | Address Setup Time to Write End | 7 | — | 9 | — | 18 | — | ns |
| t _{HA} | Address Hold from Write End | 0 | — | 0 | — | 0 | — | ns |
| t _{SA} | Address Setup Time | 0 | — | 0 | — | 0 | — | ns |
| t _{PWB} | \overline{LB} , \overline{UB} Valid to End of Write | 7 | — | 9 | — | 18 | — | ns |
| t _{PWE1} | \overline{WE} Pulse Width (\overline{OE} =High) | 7 | — | 9 | — | 15 | — | ns |
| t _{PWE2} | \overline{WE} Pulse Width (\overline{OE} =Low) | 7 | — | 9 | — | 17 | — | ns |
| t _{SD} | Data Setup to Write End | 6 | — | 6 | — | 15 | — | ns |
| t _{HD} | Data Hold from Write End | 0 | — | 0 | — | 0 | — | ns |
| t _{HZWE⁽²⁾} | \overline{WE} LOW to High-Z Output | — | 6 | — | 6 | — | 15 | ns |
| t _{LZWE⁽²⁾} | \overline{WE} HIGH to Low-Z Output | 3 | — | 3 | — | 5 | — | ns |

Notes:

1. Test conditions assume signal transition times of 3 ns or less, timing reference levels of 1.5V, input pulse levels of 0 to 3.0V and output loading specified in Figure 1.
2. Tested with the load in Figure 2. Transition is measured ± 500 mV from steady-state voltage. Not 100% tested.
3. The internal write time is defined by the overlap of \overline{CE} LOW and \overline{UB} or \overline{LB} , and \overline{WE} LOW. All signals must be in valid states to initiate a Write, but any one can go inactive to terminate the Write. The Data Input Setup and Hold timing are referenced to the rising or falling edge of the signal that terminates the write.

AC WAVEFORMS

WRITE CYCLE NO. 1 (\overline{WE} Controlled)^(1,2)



Notes:

1. WRITE is an internally generated signal asserted during an overlap of the LOW states on the \overline{CE} and \overline{WE} inputs and at least one of the \overline{LB} and \overline{UB} inputs being in the LOW state.
2. WRITE = $(\overline{CE}) [(\overline{LB}) = (\overline{UB})] (\overline{WE})$.

WRITE CYCLE NO. 2 (\overline{OE} is HIGH During Write Cycle) ^(1,2)



WRITE CYCLE NO. 3 (\overline{OE} is LOW During Write Cycle) ⁽¹⁾



Notes:

1. The internal write time is defined by the overlap of \overline{CE} LOW and \overline{WE} LOW. All signals must be in valid states to initiate a Write, but any one can go inactive to terminate the Write. The Data Input Setup and Hold timing are referenced to the rising or falling edge of the signal that terminates the Write.
2. I/O will assume the High-Z state if $\overline{OE} \geq V_{IH}$.

WRITE CYCLE NO. 4 ($\overline{UB}/\overline{LB}$ Back to Back Write)



DATA RETENTION SWITCHING CHARACTERISTICS (HIGH SPEED) (IS61/64C25616AL)

| Symbol | Parameter | Test Condition | Min. | Max. | Unit |
|-----------|-----------------------------|---|----------|------|------|
| V_{DR} | V_{DD} for Data Retention | See Data Retention Waveform | 2.9 | 5.5 | V |
| I_{DR} | Data Retention Current | $V_{DD}=2.9V, \overline{CE} \geq V_{DD}-0.2V$ $V_{IN} \geq V_{DD}-0.2V$, or $V_{IN} \leq V_{SS}+0.2V$ | — | 8 | mA |
| | | | — | 10 | |
| | | | — | 15 | |
| t_{SDR} | Data Retention Setup Time | See Data Retention Waveform | 0 | — | ns |
| t_{RDR} | Recovery Time | See Data Retention Waveform | t_{RC} | — | ns |

Note:

1. Typical Values are measured at $V_{DD}=5V, T_A=25^\circ C$ and not 100% tested.

DATA RETENTION WAVEFORM (\overline{CE} Controlled)



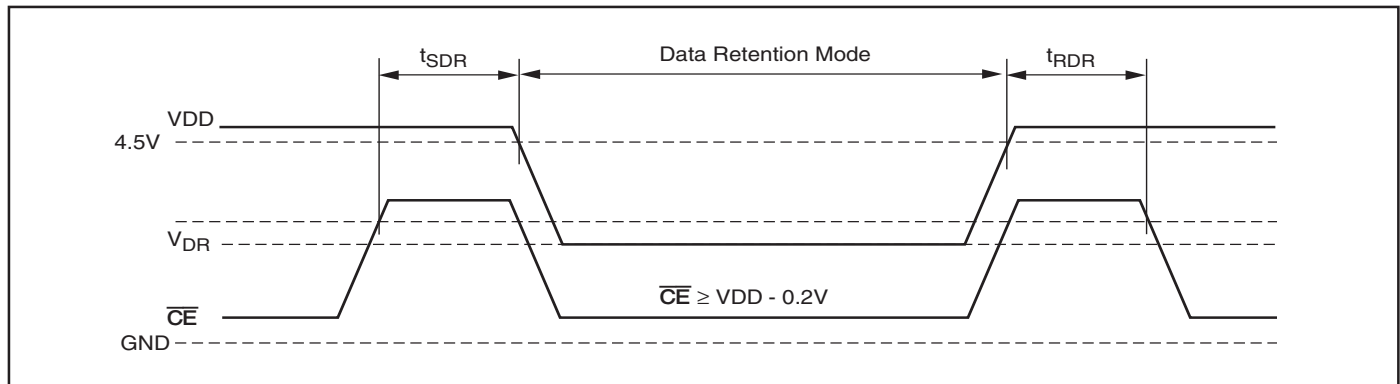
DATA RETENTION SWITCHING CHARACTERISTICS (LOW POWER) (IS61/64C25616AS)

| Symbol | Parameter | Test Condition | Min. | Max. | Unit | |
|-----------|-----------------------------|--|------------------------------|------|------|----|
| V_{DR} | V_{DD} for Data Retention | See Data Retention Waveform | 2.9 | 5.5 | V | |
| I_{DR} | Data Retention Current | $V_{DD} = 2.9V, \overline{CE} \geq V_{DD} - 0.2V$ | Com. | — | 0.8 | mA |
| | | $V_{IN} \geq V_{DD} - 0.2V, \text{ or } V_{IN} \leq V_{SS} + 0.2V$ | Ind. | — | 0.9 | |
| | | | Auto. typ. ⁽¹⁾ | — | 0.2 | |
| t_{SDR} | Data Retention Setup Time | See Data Retention Waveform | 0 | — | ns | |
| t_{RDR} | Recovery Time | See Data Retention Waveform | t_{RC} | — | ns | |

Note:

1. Typical Values are measured at $V_{DD} = 5V, T_A = 25^\circ C$ and not 100% tested.

DATA RETENTION WAVEFORM (\overline{CE} Controlled)



HIGH SPEED

ORDERING INFORMATION: IS61/64C25616AL

Commercial Range: 0°C to +70°C

| Speed (ns) | Order Part No. | Package |
|------------|-------------------|---------------------------|
| 10 | IS61C25616AL-10TL | 44-pin TSOP-II, Lead-free |

Industrial Range: -40°C to +85°C

| Speed (ns) | Order Part No. | Package |
|------------|--------------------|--------------------------------|
| 10 | IS61C25616AL-10KI | 400-mil Plastic SOJ |
| | IS61C25616AL-10KLI | 400-mil Plastic SOJ, Lead-free |
| | IS61C25616AL-10TI | 44-pin TSOP-II |
| | IS61C25616AL-10TLI | 44-pin TSOP-II, Lead-free |

Automotive Range: -40°C to +125°C

| Speed (ns) | Order Part No. | Package |
|------------|----------------------|---|
| 12 | IS64C25616AL-12KA3 | 400-mil Plastic SOJ |
| | IS64C25616AL-12TA3 | 44-pin TSOP-II |
| | IS64C25616AL-12CTLA3 | 44-pin TSOP-II, Lead-free, Copper Leadframe |

LOW POWER

ORDERING INFORMATION: IS61C25616AS

Industrial Range: -40°C to +85°C

| Speed (ns) | Order Part No. | Package |
|------------|--------------------|--------------------------------|
| 25 | IS61C25616AS-25KI | 400-mil Plastic SOJ |
| | IS61C25616AS-25KLI | 400-mil Plastic SOJ, Lead-free |
| | IS61C25616AS-25TI | 44-pin TSOP-II |
| | IS61C25616AS-25TLI | 44-pin TSOP-II, Lead-free |

Automotive Range: -40°C to +125°C

| Speed (ns) | Order Part No. | Package |
|------------|---------------------|---------------------------|
| 25 | IS64C25616AS-25TLA3 | 44-pin TSOP-II, Lead-free |

PACKAGING INFORMATION

400-mil Plastic SOJ

Package Code: K



Notes:

1. Controlling dimension: millimeters.
2. BSC = Basic lead spacing between centers.
3. Dimensions D and E1 do not include mold flash protrusions and should be measured from the bottom of the package.
4. Reference document: JEDEC MS-027.

| Symbol | Millimeters | | Inches | | Millimeters | | Inches | | Millimeters | | Inches | |
|---------------|-------------|-------|-----------|-------|-------------|-------|-----------|-------|-------------|-------|-----------|-------|
| | Min | Max | Min | Max | Min | Max | Min | Max | Min | Max | Min | Max |
| No. Leads (N) | 28 | | | | 32 | | | | 36 | | | |
| A | 3.25 | 3.75 | 0.128 | 0.148 | 3.25 | 3.75 | 0.128 | 0.148 | 3.25 | 3.75 | 0.128 | 0.148 |
| A1 | 0.64 | — | 0.025 | — | 0.64 | — | 0.025 | — | 0.64 | — | 0.025 | — |
| A2 | 2.08 | — | 0.082 | — | 2.08 | — | 0.082 | — | 2.08 | — | 0.082 | — |
| B | 0.38 | 0.51 | 0.015 | 0.020 | 0.38 | 0.51 | 0.015 | 0.020 | 0.38 | 0.51 | 0.015 | 0.020 |
| b | 0.66 | 0.81 | 0.026 | 0.032 | 0.66 | 0.81 | 0.026 | 0.032 | 0.66 | 0.81 | 0.026 | 0.032 |
| C | 0.18 | 0.33 | 0.007 | 0.013 | 0.18 | 0.33 | 0.007 | 0.013 | 0.18 | 0.33 | 0.007 | 0.013 |
| D | 18.29 | 18.54 | 0.720 | 0.730 | 20.82 | 21.08 | 0.820 | 0.830 | 23.37 | 23.62 | 0.920 | 0.930 |
| E | 11.05 | 11.30 | 0.435 | 0.445 | 11.05 | 11.30 | 0.435 | 0.445 | 11.05 | 11.30 | 0.435 | 0.445 |
| E1 | 10.03 | 10.29 | 0.395 | 0.405 | 10.03 | 10.29 | 0.395 | 0.405 | 10.03 | 10.29 | 0.395 | 0.405 |
| E2 | 9.40 BSC | | 0.370 BSC | | 9.40 BSC | | 0.370 BSC | | 9.40 BSC | | 0.370 BSC | |
| e | 1.27 BSC | | 0.050 BSC | | 1.27 BSC | | 0.050 BSC | | 1.27 BSC | | 0.050 BSC | |

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Rev. F
10/29/03



PACKAGING INFORMATION

| Symbol | Millimeters | | Inches | | Millimeters | | Inches | | Millimeters | | Inches | |
|---------------|-------------|-------|-----------|-------|-------------|-------|-----------|-------|-------------|-------|-----------|-------|
| | Min | Max | Min | Max | Min | Max | Min | Max | Min | Max | Min | Max |
| No. Leads (N) | 40 | | | | 42 | | | | 44 | | | |
| A | 3.25 | 3.75 | 0.128 | 0.148 | 3.25 | 3.75 | 0.128 | 0.148 | 3.25 | 3.75 | 0.128 | 0.148 |
| A1 | 0.64 | — | 0.025 | — | 0.64 | — | 0.025 | — | 0.64 | — | 0.025 | — |
| A2 | 2.08 | — | 0.082 | — | 2.08 | — | 0.082 | — | 2.08 | — | 0.082 | — |
| B | 0.38 | 0.51 | 0.015 | 0.020 | 0.38 | 0.51 | 0.015 | 0.020 | 0.38 | 0.51 | 0.015 | 0.020 |
| b | 0.66 | 0.81 | 0.026 | 0.032 | 0.66 | 0.81 | 0.026 | 0.032 | 0.66 | 0.81 | 0.026 | 0.032 |
| C | 0.18 | 0.33 | 0.007 | 0.013 | 0.18 | 0.33 | 0.007 | 0.013 | 0.18 | 0.33 | 0.007 | 0.013 |
| D | 25.91 | 26.16 | 1.020 | 1.030 | 27.18 | 27.43 | 1.070 | 1.080 | 28.45 | 28.70 | 1.120 | 1.130 |
| E | 11.05 | 11.30 | 0.435 | 0.445 | 11.05 | 11.30 | 0.435 | 0.445 | 11.05 | 11.30 | 0.435 | 0.445 |
| E1 | 10.03 | 10.29 | 0.395 | 0.405 | 10.03 | 10.29 | 0.395 | 0.405 | 10.03 | 10.29 | 0.395 | 0.405 |
| E2 | 9.40 BSC | | 0.370 BSC | | 9.40 BSC | | 0.370 BSC | | 9.40 BSC | | 0.370 BSC | |
| e | 1.27 BSC | | 0.050 BSC | | 1.27 BSC | | 0.050 BSC | | 1.27 BSC | | 0.050 BSC | |

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PACKAGING INFORMATION

Plastic TSOP
 Package Code: T (Type II)



Notes:

1. Controlling dimension: millimeters, unless otherwise specified.
2. BSC = Basic lead spacing between centers.
3. Dimensions D and E1 do not include mold flash protrusions and should be measured from the bottom of the package.
4. Formed leads shall be planar with respect to one another within 0.004 inches at the seating plane.



Plastic TSOP (T - Type II)

| Symbol | Millimeters | | Inches | | Millimeters | | Inches | | Millimeters | | Inches | |
|---------------|-------------|-------|-----------|-------|-------------|-------|-----------|-------|-------------|-------|-----------|-------|
| | Min | Max | Min | Max | Min | Max | Min | Max | Min | Max | Min | Max |
| Ref. Std. | | | | | | | | | | | | |
| No. Leads (N) | 32 | | | | 44 | | | | 50 | | | |
| A | — | 1.20 | — | 0.047 | — | 1.20 | — | 0.047 | — | 1.20 | — | 0.047 |
| A1 | 0.05 | 0.15 | 0.002 | 0.006 | 0.05 | 0.15 | 0.002 | 0.006 | 0.05 | 0.15 | 0.002 | 0.006 |
| b | 0.30 | 0.52 | 0.012 | 0.020 | 0.30 | 0.45 | 0.012 | 0.018 | 0.30 | 0.45 | 0.012 | 0.018 |
| C | 0.12 | 0.21 | 0.005 | 0.008 | 0.12 | 0.21 | 0.005 | 0.008 | 0.12 | 0.21 | 0.005 | 0.008 |
| D | 20.82 | 21.08 | 0.820 | 0.830 | 18.31 | 18.52 | 0.721 | 0.729 | 20.82 | 21.08 | 0.820 | 0.830 |
| E1 | 10.03 | 10.29 | 0.391 | 0.400 | 10.03 | 10.29 | 0.395 | 0.405 | 10.03 | 10.29 | 0.395 | 0.405 |
| E | 11.56 | 11.96 | 0.451 | 0.466 | 11.56 | 11.96 | 0.455 | 0.471 | 11.56 | 11.96 | 0.455 | 0.471 |
| e | 1.27 BSC | | 0.050 BSC | | 0.80 BSC | | 0.032 BSC | | 0.80 BSC | | 0.031 BSC | |
| L | 0.40 | 0.60 | 0.016 | 0.024 | 0.41 | 0.60 | 0.016 | 0.024 | 0.40 | 0.60 | 0.016 | 0.024 |
| ZD | 0.95 REF | | 0.037 REF | | 0.81 REF | | 0.032 REF | | 0.88 REF | | 0.035 REF | |
| α | 0° | 5° | 0° | 5° | 0° | 5° | 0° | 5° | 0° | 5° | 0° | 5° |

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